

MOSFETs Silicon N-channel MOS (U-MOS^Ⅷ)

TPN2R203NC

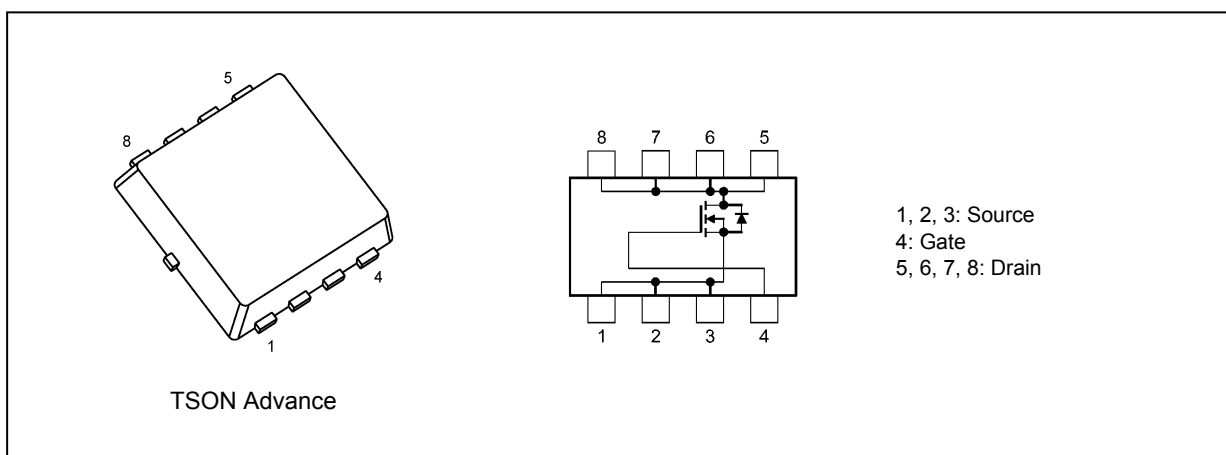
1. Applications

- Power Management Switches

2. Features

- Low drain-source on-resistance: $R_{DS(ON)} = 1.8 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- Low leakage current: $I_{DSS} = 10 \text{ }\mu\text{A}$ (max) ($V_{DS} = 30 \text{ V}$)
- Enhancement mode: $V_{th} = 1.3 \text{ to } 2.3 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 0.5 \text{ mA}$)

3. Packaging and Internal Circuit



4. Absolute Maximum Ratings (Note) ($T_a = 25 \text{ }^\circ\text{C}$ unless otherwise specified)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	30	V
Gate-source voltage	V_{GSS}	± 20	V
Drain current (DC) (Silicon limit) (Note 1), (Note 2)	I_D	100	A
Drain current (DC) ($T_c = 25 \text{ }^\circ\text{C}$) (Note 1)	I_D	45	A
Drain current (pulsed) ($t = 1 \text{ ms}$) (Note 1)	I_{DP}	200	A
Power dissipation ($T_c = 25 \text{ }^\circ\text{C}$)	P_D	42	W
Power dissipation ($t = 10 \text{ s}$) (Note 3)	P_D	1.9	W
Power dissipation ($t = 10 \text{ s}$) (Note 4)	P_D	0.7	W
Single-pulse avalanche energy (Note 5)	E_{AS}	126	mJ
Avalanche current	I_{AR}	45	A
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to 150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Start of commercial production

2013-05

5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance ($T_c = 25\text{ }^{\circ}\text{C}$)	$R_{th(ch-c)}$	2.97	$^{\circ}\text{C/W}$
Channel-to-ambient thermal resistance ($t = 10\text{ s}$) (Note 3)	$R_{th(ch-a)}$	65.7	$^{\circ}\text{C/W}$
Channel-to-ambient thermal resistance ($t = 10\text{ s}$) (Note 4)	$R_{th(ch-a)}$	178	$^{\circ}\text{C/W}$

Note 1: Ensure that the channel temperature does not exceed $150\text{ }^{\circ}\text{C}$.

Note 2: Limited by silicon chip capability.

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: $V_{DD} = 24\text{ V}$, $T_{ch} = 25\text{ }^{\circ}\text{C}$ (initial), $L = 0.048\text{ mH}$, $I_{AR} = 45\text{ A}$



Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)



Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

6. Electrical Characteristics

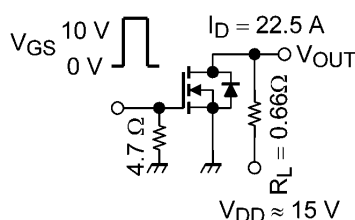
6.1. Static Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current	I_{GSS}	$V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$	—	—	± 0.1	μA
Drain cut-off current	I_{DSS}	$V_{DS} = 30\text{ V}$, $V_{GS} = 0\text{ V}$	—	—	10	μA
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 10\text{ mA}$, $V_{GS} = 0\text{ V}$	30	—	—	V
Drain-source breakdown voltage (Note 6)	$V_{(BR)DSX}$	$I_D = 10\text{ mA}$, $V_{GS} = -20\text{ V}$	15	—	—	V
Gate threshold voltage	V_{th}	$V_{DS} = 10\text{ V}$, $I_D = 0.5\text{ mA}$	1.3	—	2.3	V
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 4.5\text{ V}$, $I_D = 22.5\text{ A}$	—	2.8	3.6	$\text{m}\Omega$
Drain-source on-resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{ V}$, $I_D = 22.5\text{ A}$	—	1.8	2.2	$\text{m}\Omega$

Note 6: If a reverse bias is applied between gate and source, this device enters $V_{(BR)DSX}$ mode. Note that the drain-source breakdown voltage is lowered in this mode.

6.2. Dynamic Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Input capacitance	C_{iss}	$V_{DS} = 15\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	—	2230	—	pF
Reverse transfer capacitance	C_{rss}		—	160	—	pF
Output capacitance	C_{oss}		—	650	—	pF
Switching time (rise time)	t_r	See Fig. 6.2.1	—	9	—	ns
Switching time (turn-on time)	t_{on}		—	14	—	ns
Switching time (fall time)	t_f		—	24	—	ns
Switching time (turn-off time)	t_{off}		—	68	—	ns



Duty $\leq 1\%$, $t_w = 10\text{ }\mu\text{s}$

Fig. 6.2.1 Switching Time Test Circuit

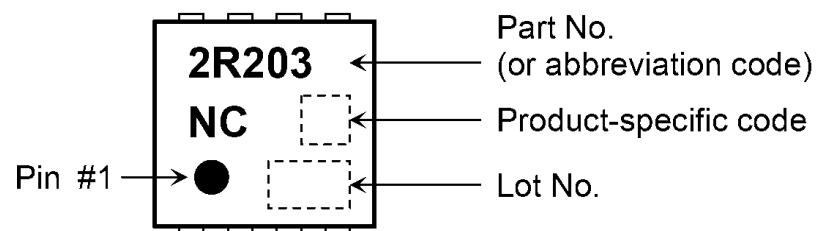
6.3. Gate Charge Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 15\text{ V}$, $V_{GS} = 10\text{ V}$, $I_D = 45\text{ A}$	—	34	—	nC
Gate-source charge 1	Q_{gs1}		—	8	—	nC
Gate-drain charge	Q_{gd}		—	6	—	nC

6.4. Source-Drain Characteristics ($T_a = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Reverse drain current (pulsed) (1 ms) (Note 7)	I_{DRP}	—	—	—	200	A
Diode forward voltage	V_{DSF}	$I_{DR} = 45\text{ A}$, $V_{GS} = 0\text{ V}$	—	—	-1.2	V

Note 7: Ensure that the channel temperature does not exceed $150\text{ }^{\circ}\text{C}$.

7. Marking**Fig. 7.1 Marking**

8. Characteristics Curves (Note)

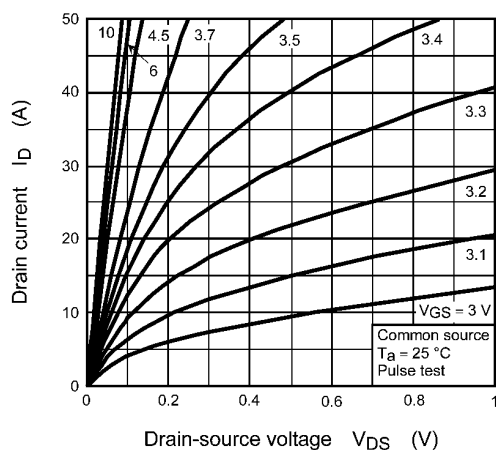


Fig. 8.1 $I_D - V_{DS}$

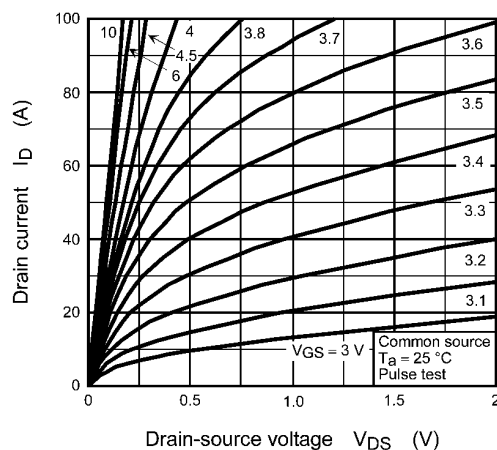


Fig. 8.2 $I_D - V_{DS}$

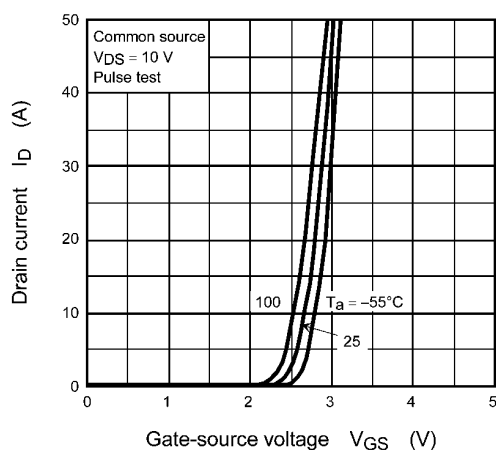


Fig. 8.3 $I_D - V_{GS}$

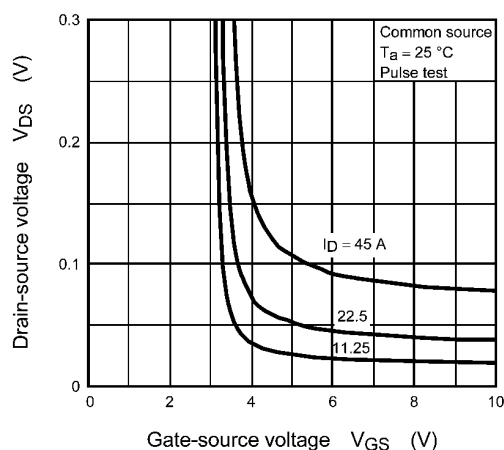


Fig. 8.4 $V_{DS} - V_{GS}$

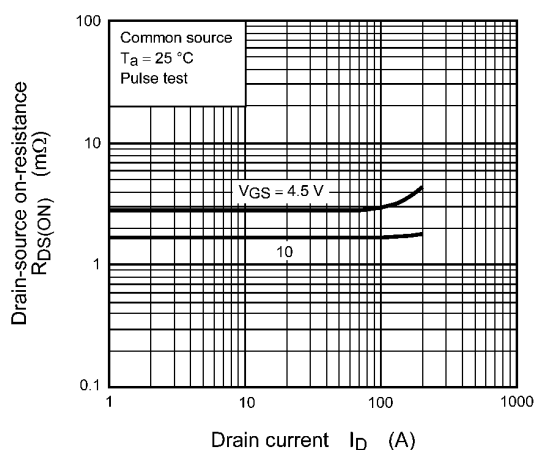


Fig. 8.5 $R_{DS(ON)} - I_D$

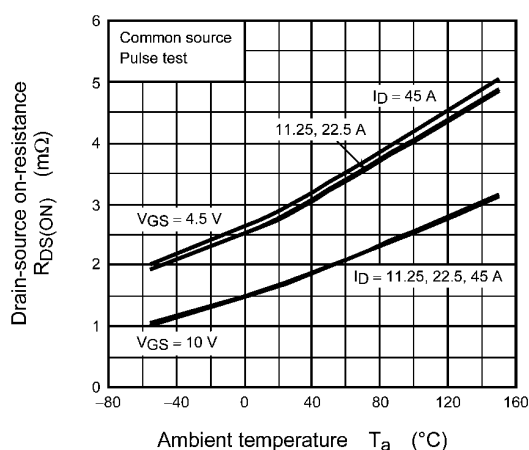


Fig. 8.6 $R_{DS(ON)} - T_a$

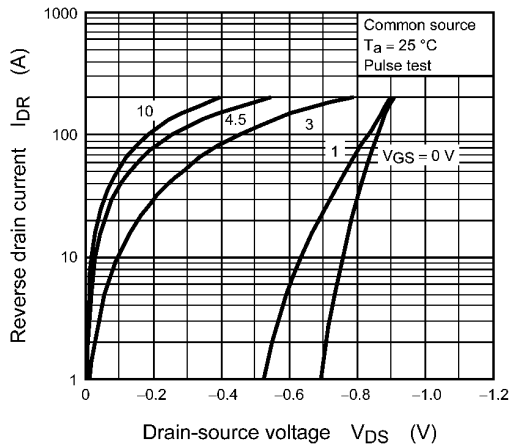


Fig. 8.7 $I_{DR} - V_{DS}$

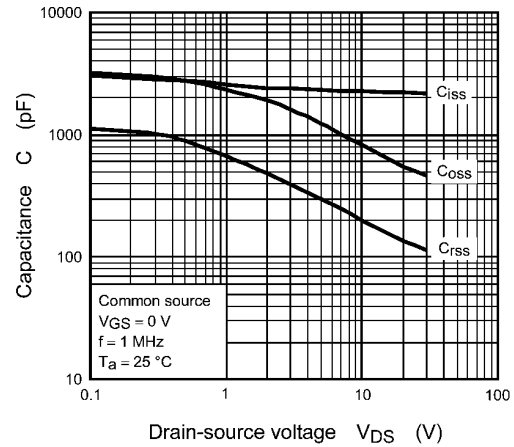


Fig. 8.8 Capacitance - V_{DS}

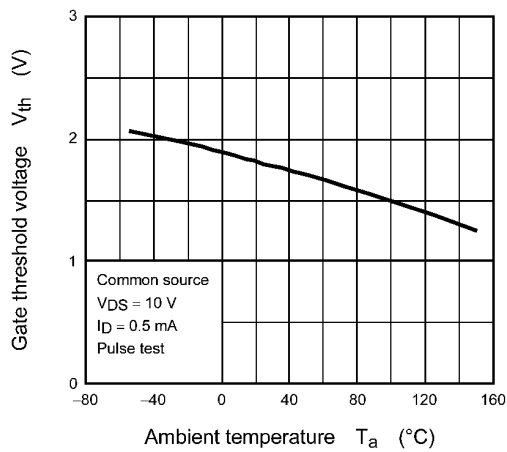


Fig. 8.9 $V_{th} - T_a$

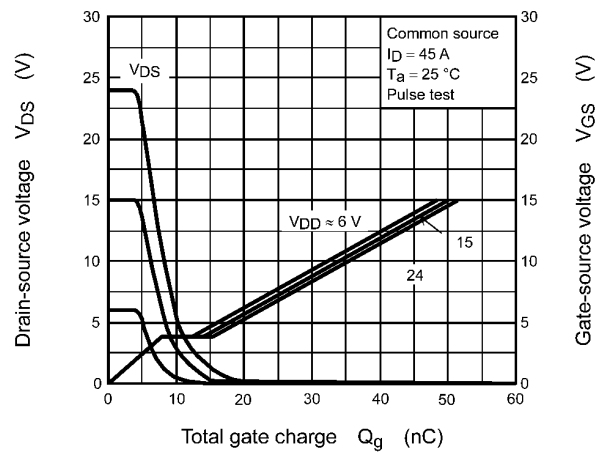
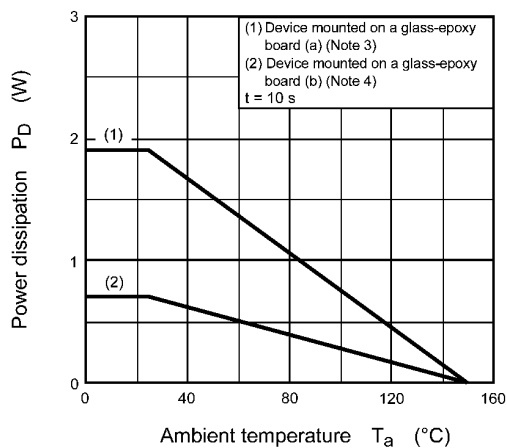
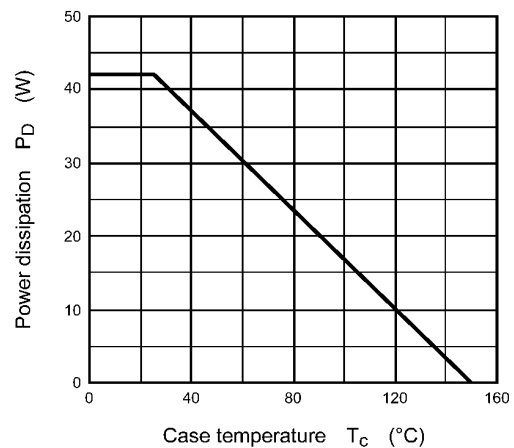


Fig. 8.10 Dynamic Input/Output Characteristics



**Fig. 8.11 $P_D - T_a$
(Guaranteed Maximum)**



**Fig. 8.12 $P_D - T_c$
(Guaranteed Maximum)**

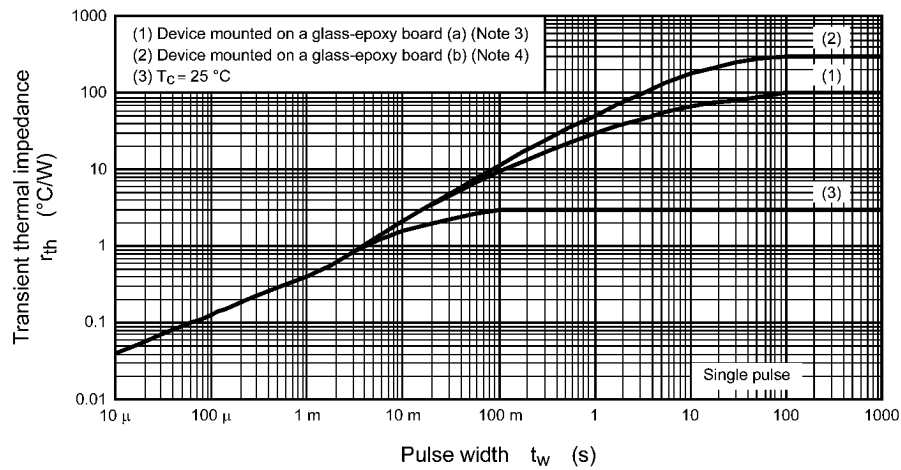


Fig. 8.13 $r_{th} - t_w$
 (Guaranteed Maximum)

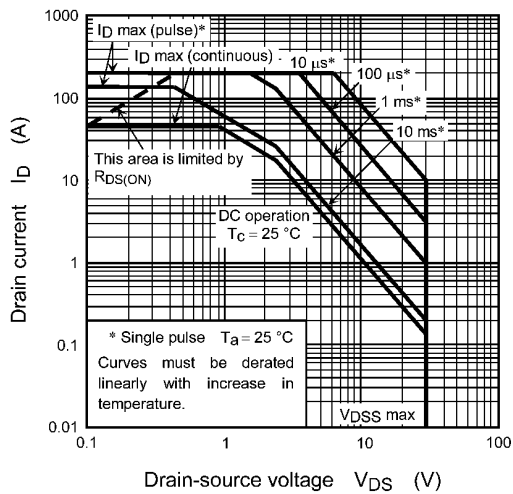
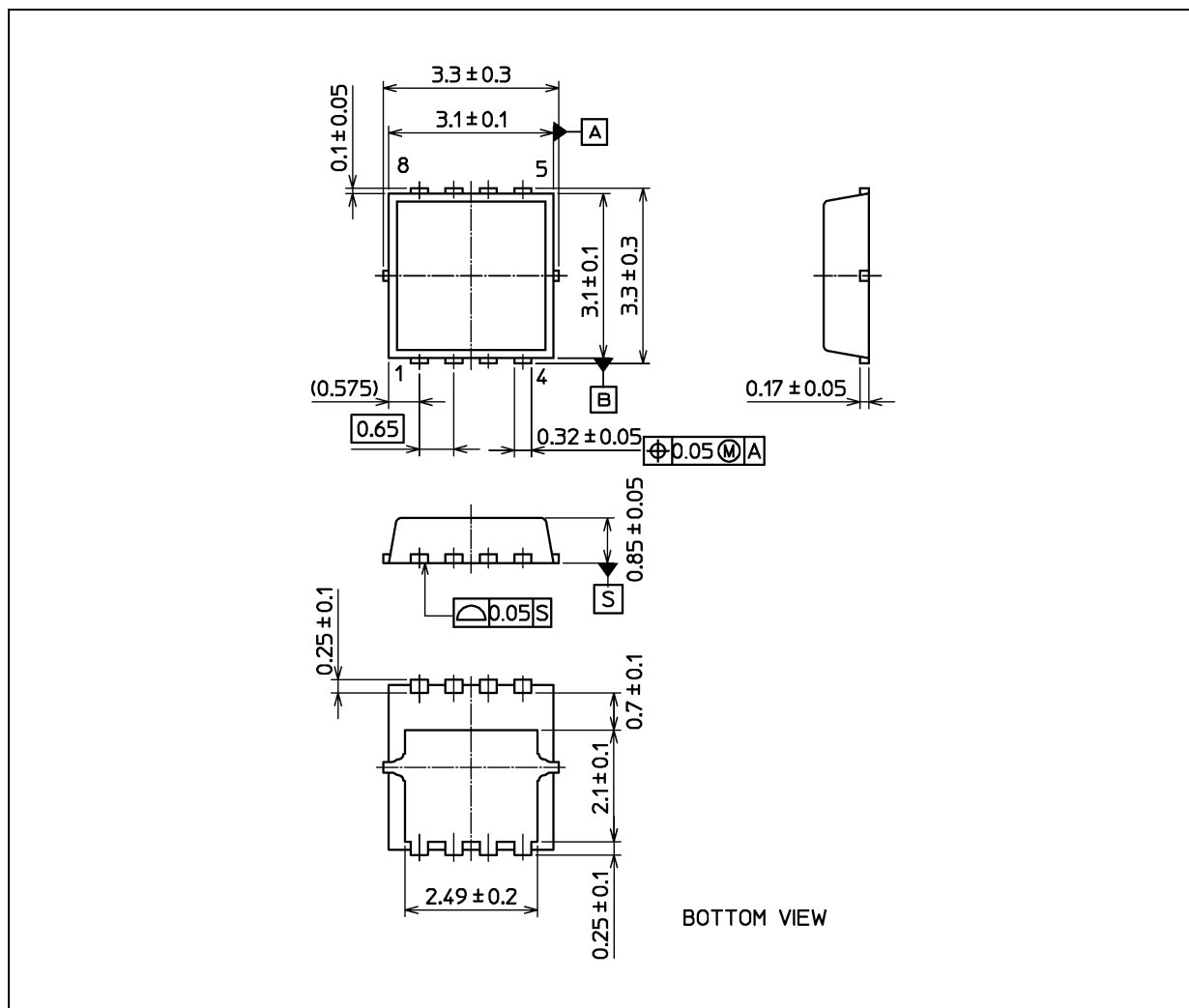


Fig. 8.14 Safe Operating Area
 (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 0.02 g (typ.)

Package Name(s)
TOSHIBA: 2-3X1S
Nickname: TSON Advance

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